



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Rodney C. Langley

Serial No.: 09/438,692

Filed: November 11, 1999

For: SEMICONDUCTOR DEVICE WITH
IMPROVED BOND PADS

Confirmation No.: 9759

Examiner: R. Potter

Group Art Unit: 2822

Attorney Docket No.: 2269-3656US
(95-0028.RE)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

October 14, 2005
Date

Emily Stevens
Name (Type/Print)

SUPPLEMENTAL REISSUE DECLARATION

Commissioner for Patents
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Sir:

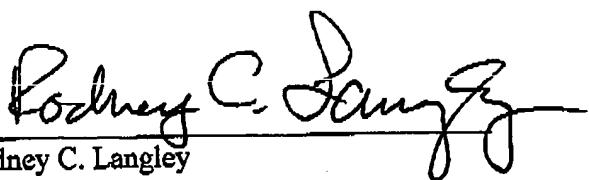
I hereby declare that:

Every error in the patent which was corrected in the present reissue application up to the time(s) of execution of this declaration, and which is not covered by the prior oath(s) and/or declaration(s) submitted in this application, arose without any deceptive intention on the part of the applicant.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are

punishable by fine or imprisonment, or both, under 18 U.S.C. 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Date: 10-14-05


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